

Title (en)
PROCESS FOR THE NON-GALVANIC TIN PLATING OF COPPER OR COPPER ALLOYS

Title (de)
VERFAHREN ZUR STROMLOSEN VERZINNUNG VON KUPFER ODER KUPFERLEGIERUNGEN

Title (fr)
PROCEDE DESTINE A L'ETAMAGE NON GALVANIQUE DU CUIVRE OU D'ALLIAGES DE CUIVRE

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Abstract (en)
[origin: WO0134310A1] The invention describes a process for non-galvanic tin plating of copper and copper alloys by precipitation of tin from methanesulphonic acid and tin-containing electrolytes, containing a complexing agent. In describing a process by which a durable tin layer which can be soldered is created, which, at the same time, prevents liberation of the base material, this invention discloses that the electrolytes have at least one foreign metal added to form a diffusion barrier in the tin layer.

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Citation (third parties)
Third party :
• JP H09302476 A 19971125 - DAIWA KASEI KENKYUSHO
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• JP H0339488 A 19910220 - UEMURA KOGYO KK
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• US 4749626 A 19880607 - KADIJA IGOR V [US], et al
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• DR. MANFRED JORDAN: "The Electrodeposition of Tin and its Alloys", March 1992, EUGEN G. LEUZEN PUBLISHERS, ISBN: 3-87480-118-7, article "Whiskers", XP003025396

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